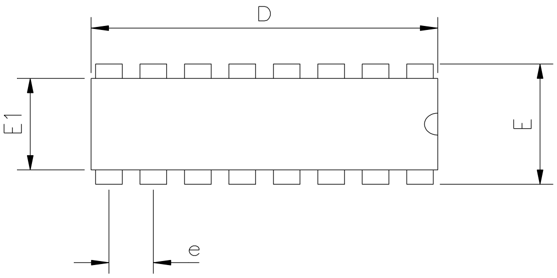
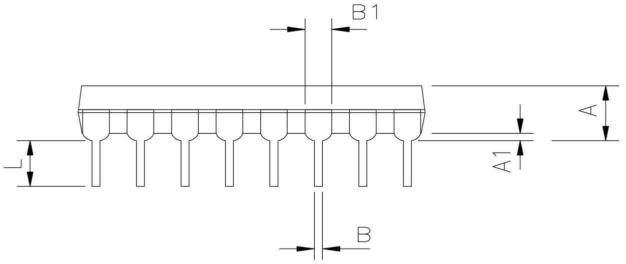
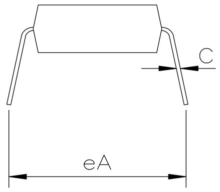
600 MIL PDIP

PLASTIC DUAL IN-LINE PACKAGE

PACKAGE INFORMATION







NOTES

1. SPADE WIDTH, LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. TOLERANCE AS PER LEAD FRAME SUPPLIER
4. PACKAGE FINISH–MATTE FINISH ON ALL SIDES(8±2 MICRONS Rz)
5. ALLOWABLE MOLD FLASH IS 10 MILS PER SIDE.
6. DIMENSIONS ARE GIVEN IN INCHES.

JEDEC #	–		–		–		–	
TYPE	24 LEAD		28 LEAD		40 LEAD		48 LEAD	
SYMBOL	Min	Max	Min	Max	Min	Max	Min	Max
A	0.150	0.190	0.150	0.190	0.150	0.190	0.150	0.190
A1	0.015	0.040	0.015	0.040	0.015	0.040	0.015	0.040
B	0.016	0.020	0.016	0.020	0.016	0.020	0.016	0.020
B1	0.045	0.070	0.045	0.070	0.045	0.070	0.045	0.070
C	0.009	0.012	0.009	0.012	0.009	0.012	0.009	0.012
D	1.240	1.250	1.440	1.460	2.050	2.060	2.420	2.430
E	0.600	0.625	0.600	0.625	0.600	0.625	0.600	0.625
E1	0.530	0.560	0.530	0.560	0.530	0.560	0.530	0.560
e	0.090	0.110	0.090	0.110	0.090	0.110	0.090	0.110
eA	0.610	0.680	0.610	0.680	0.610	0.680	0.610	0.680
L	0.120	0.140	0.120	0.140	0.120	0.140	0.120	0.140

PREPARED BY	NK	REF. NO.	REV. NO.	SPEL SEMICONDUCTOR LIMITED
CHECKED BY	NJC	DIM–PDIP–02	0	INDIA
APPROVED BY	RM		DATE 17.08.96	